

C0402C393J4RACTU

Aliases (C0402C393J4RAC7867) SMD Comm X7R, Ceramic, 0.039 uF, 5%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0402, 0.3 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X7R	
Style	SMD Chip	
Description	SMD, MLCC, Temperature Stable, Class II	
Features	Temperature Stable, Class II	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	1.21 mg	
Shelf Life	78 Weeks	
MSL	1	

3.5%1kHz1.0Vrms

10 GOhms

3% Loss/Decade Hour: Referee Time is 1000 Hours

		Specifications	
	0402	Capacitance	0.039 uF
	1mm +/-0.05mm	Measurement Condition	1 kHz 1.0Vrms
	0.5mm +/-0.05mm	Tolerance	5%
	0.5mm +/-0.05mm	Voltage DC	16 VDC
	0.3mm MIN	Dielectric Withstanding Voltage	40 VDC
	0.3mm +/-0.1mm	Temperature Range	-55/+125°C
		Temp. Coefficient	X7R
		Capacitance Change with	15%, 1kHz 1.0Vrms
	T&R, 180mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)	
10000	Dissipation Factor	3 5% 1kHz 10\/rms	

Dissipation Factor

Insulation Resistance

Aging Rate

Dimensions Chip Size L W Т s

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	10000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

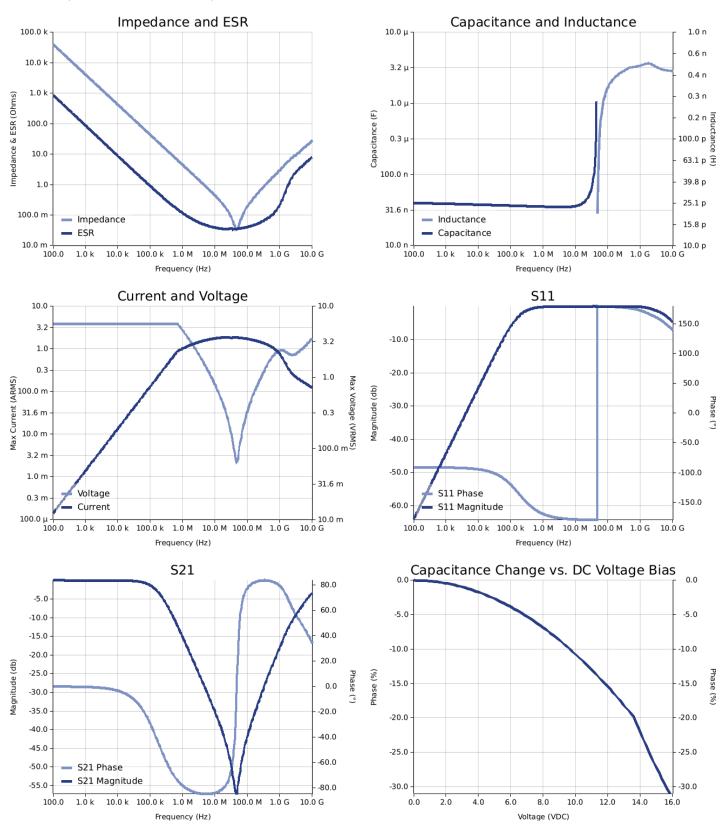
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CO402C393J4RACTU Aliases (C0402C393J4RAC7867) SMD Comm X7R, Ceramic, 0.039 uF, 5%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0402, 0.3 mm

Simulations

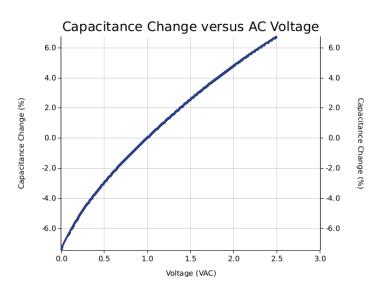
For the complete simulation environment please visit K-SIM.



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current/ voltage vs. requericy plots is the ESR at an originatine.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages are applied to reach previous the burger of the parts.
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.